

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) An organic positive temperature coefficient thermistor device comprising a pair of electrodes disposed so as to oppose each other, and a thermistor body having a positive resistance-temperature characteristic disposed between the electrodes, wherein the thermistor body consists of a cured product of a mixture containing an epoxy resin including a flexible epoxy resin, a curing agent, and an electrically conductive particle.

2. (Original) An organic positive temperature coefficient thermistor device according to claim 1, wherein the epoxy resin includes 3 to 100 % by mass of the flexible epoxy resin based on the total mass of the epoxy resin.

3. (Original) An organic positive temperature coefficient thermistor device comprising a pair of electrodes disposed so as to oppose each other, and a thermistor body having a positive resistance-temperature characteristic disposed between the electrodes, wherein the thermistor body consists of a cured product of a mixture containing a flexible epoxy resin having a bending elasticity of 2700 MPa or less and an electrically conductive particle.

4. (Currently Amended) An organic positive temperature coefficient thermistor device according to ~~any of claims 1 to 3~~claim 1, wherein the conductive particle has a surface provided with a protrusion.

5. (New) An organic positive temperature coefficient thermistor device according to claim 2, wherein the conductive particle has a surface provided with a protrusion.

6. (New) An organic positive temperature coefficient thermistor device according to claim 3, wherein the conductive particle has a surface provided with a protrusion.

